Abstracts

Impact of test-fixture forward coupling on on-wafer silicon device measurements

T.E. Kolding. "Impact of test-fixture forward coupling on on-wafer silicon device measurements." 2000 Microwave and Guided Wave Letters 10.2 (Feb. 2000 [MGWL]): 73-74.

Often, the test-fixture forward coupling is ignored during on-wafer device measurements, although existing de-embedding techniques provide means for addressing its effect. In this work it is demonstrated that large errors may occur if forward coupling is not determined and accounted for. An investigation based on basic scaling properties of MOSFETs is proposed as a benchmark test to partially verify de-embedding methods.

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